Power MOSFET

-20 V, -5.5 A, Single P-Channel 2.4 x 2.9 x 1.0 mm SOT-23 Package

Features

- Low R_{DS(on)} Solution in 2.4 mm x 2.9 mm Package
- ESD Diode-Protected Gate
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- High Side Load Switch
- Battery Switch
- Optimized for Power Management Applications for Portable Products, such as Smart Phones, Media Tablets, PMP, DSC, GPS, and Others

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise stated)

Paramet	Symbol	Value	Unit			
Drain-to-Source Voltage	V _{DSS}	-20	V			
Gate-to-Source Voltage	V _{GS}	±8	V			
Drain Current (Note 1)	, , ,		I _D	-3.0	Α	
Drain Current (Note 1)	State	T _A = 85°C		-2.2		
	t ≤ 5 s	T _A = 25°C		-5.5		
Power Dissipation (Note 1)			P_{D}	0.48	W	
	t ≤ 5 s			1.58		
Pulsed Drain Current	I _{DM}	-9.1	Α			
Operating Junction and Sto	T _J , T _{STG}	–55 to 150	°C			
ESD HBM, JESD22-A114	V _{ESD}	2000	V			
Source Current (Body Diod	IS	-0.48	Α			
Lead Temperature for Sold (1/8 in from case for 10 s)	TL	260	°C			

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	260	°C/W
Junction-to-Ambient – $t \le 5$ s (Note 1)	$R_{\theta JA}$	79	

- Surface-mounted on FR4 board using 1 in sq. pad size (Cu area = 1.127 in sq. [2 oz] including traces).
- 2. Pulse Test: pulse width ≤ 300 ms, duty cycle ≤ 2%.

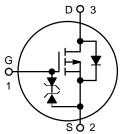


ON Semiconductor®

www.onsemi.com

V _{(BR)DSS}	V _{(BR)DSS} R _{DS(on)} Max	
	38 mΩ @ -4.5 V	
–20 V	50 mΩ @ -2.5 V	–5.5 A
	73 mΩ @ –1.8 V	

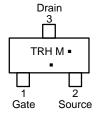
P-Channel MOSFET



MARKING DIAGRAM & PIN ASSIGNMENT



SOT-23 CASE 318 STYLE 21



TRH = Specific Device Code

M = Date Code*

= Pb–Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NTR3A30PZT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	-				-	<u>-</u>	<u> </u>
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		-20			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = -250 μA, ref	f to 25°C		10.5		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 \text{ V},$ $V_{DS} = -20 \text{ V}$ $T_{J} = 25^{\circ}\text{C}$				-1	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS}$	= ±5 V			±10	μΑ
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$	–250 μΑ	-0.4	-0.65	-1.0	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				10.5		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = -4.5 V	I _D = -3 A		31	38	mΩ
		V _{GS} = -2.5 V	$I_D = -2.5 A$		36	50	
		$V_{GS} = -1.8 \text{ V}$	$I_D = -1.5 A$		51	73	
Forward Transconductance	9FS	$V_{DS} = -5 \text{ V}, I_{D}$	= -3 A		30		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{iss}				1651		pF
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz, } V_{DS} = -15 \text{ V}$			148]
Reverse Transfer Capacitance	C _{rss}				129		
Total Gate Charge	Q _{G(TOT)}				17.6		nC
Threshold Gate Charge	Q _{G(TH)}	$V_{GS} = -4.5 \text{ V}, V_{DS} = -15 \text{ V}, I_{D} = -3 \text{ A}$			0.7		
Gate-to-Source Charge	Q _{GS}	v _{GS} = -4.5 v, v _{DS} = -	15 V, ID = -3 A		2.4		
Gate-to-Drain Charge	Q_{GD}				4.9		<u></u>
SWITCHING CHARACTERISTICS (Note	e 4)						
Turn-On Delay Time	t _{d(on)}				100		ns
Rise Time	t _r	$V_{GS} = -4.5 \text{ V}, V_{DS} = -15 \text{ V},$ $I_{D} = -3 \text{ A}, R_{G} = 6.0 \Omega$			208]
Turn-Off Delay Time	t _{d(off)}				1043		
Fall Time	t _f				552		
DRAIN-SOURCE DIODE CHARACTER	ISTICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	T _J = 25°C		0.65	1.0	V
		$I_{S} = -0.4 \text{ A}$	T _J = 125°C	_	0.47		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width ≤ 300 ms, duty cycle ≤ 2%.

4. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

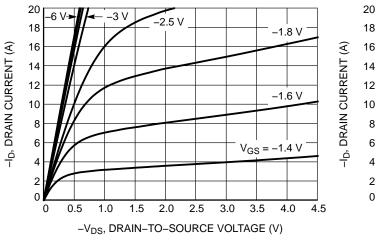


Figure 1. On-Region Characteristics

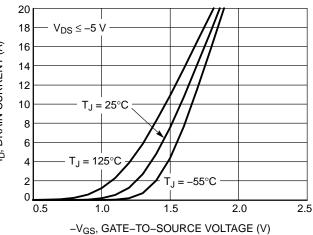


Figure 2. Transfer Characteristics

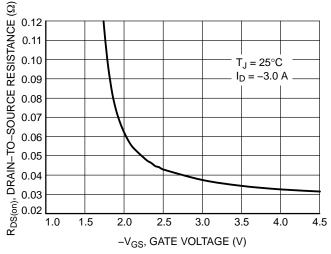


Figure 3. On–Resistance vs. Gate–to–Source Voltage

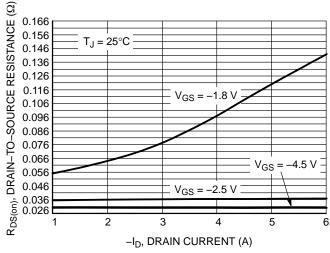


Figure 4. On–Resistance vs. Drain Current and Gate Voltage

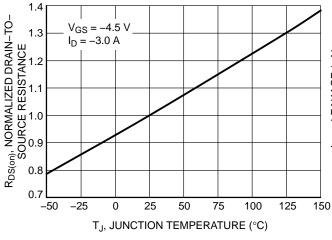


Figure 5. On–Resistance Variation with Temperature

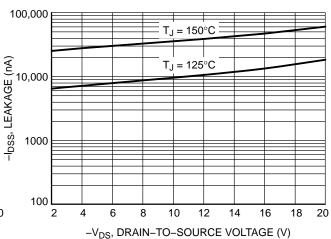


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

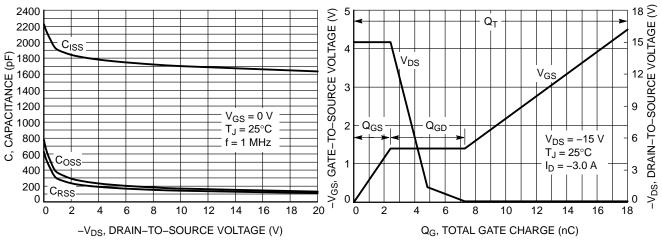


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

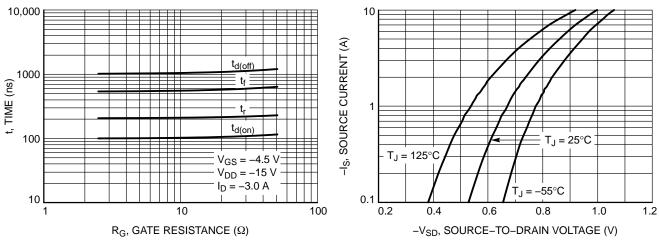


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Voltage vs. Current

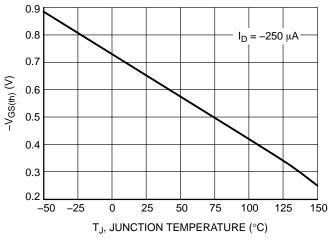


Figure 11. Threshold Voltage

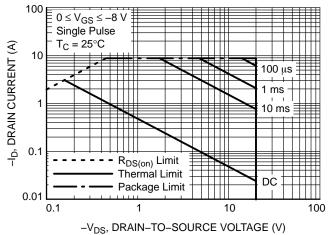


Figure 12. Maximum Rated Forward Biased Safe Operating Area

TYPICAL CHARACTERISTICS

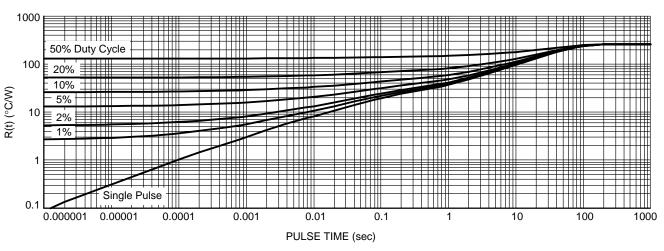
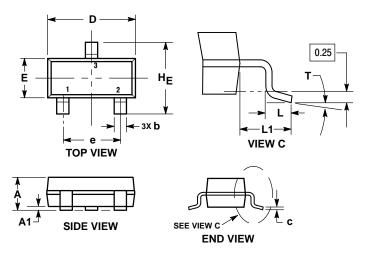


Figure 13. FET Thermal Response

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR**



- TES:
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
- THE BASE MATERIAL.

 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR GATE BURRS.

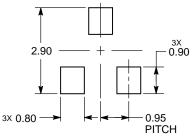
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10°	0°		10°

STYLE 21:

PIN 1. GATE 2. SOURCE

DRAIN

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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